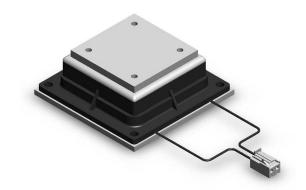


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date 07/2008

PART NUMBER: CPM-2F DESCRIPTION: peltier cooling unit

CUI's patented CPM-2 series cooling modules incorporate peltier technology in a convenient package that maximizes heat absorption and reduces overall assembly cost. The CPM-2 is assembled with our high performance peltier device between two precision-machined aluminum plates using thermally-conductive adhesive, leading to better heat transfer between the cooling and radiating surfaces. This module is perfect for applications such as refrigeration, lasers, dehumidifiers, NEMA enclosures, or any other electronic device that requires reliable, precision cooling.

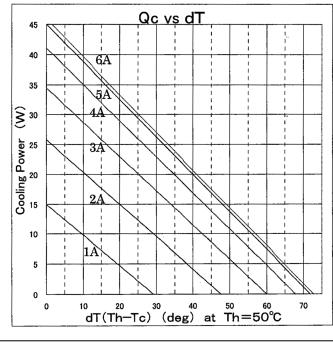


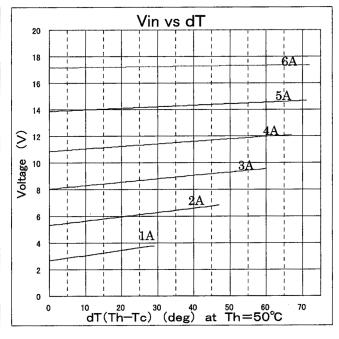
specifications

max input voltage 1	12 V dc
max current	6 A
max temp drop (ΔTmax)	73K (at Th=50° C)
max cooling power (Qmax)	46 W (at Th=Tc=50° C)
dielectric strength	1200 V ac, 1 sec.
insulation resistance	250 V dc, >10 M ohm
internal resistance ²	1.85 ~ 2.35 ohm
cold plate temperature	-20°C ~ +60° C
storage temperature	-20°C ~ +70° C
operating temperature	0°C ~ +35° C
storage humidity	10~90%
operating humidity	30~85%
weight	200g
cooling medium	aluminum plate
heat radiation medium	aluminum plate

notes: 1. at inverse voltage "cold plate" becomes heat radiation plate

performance graphs





^{2.} ambient temperature 25+/-1C, measured by 4 AC thermal method

